

HIGH PERFORMANCE COMPUTING  
FOR MANUFACTURING  
INTERNSHIP PROGRAM

# HPC4MFG

APPLICATION DEADLINE  
JANUARY 27, 2023 | 5:00 PM EST

**APPLY NOW**

[WWW.ZINTELLECT.COM/OPPORTUNITY/DETAILS/DOE-EERE-HPC-2023](http://WWW.ZINTELLECT.COM/OPPORTUNITY/DETAILS/DOE-EERE-HPC-2023)

## ELIGIBILITY

- A U.S. citizen
- At least 18 years old by May 1, 2023
- Undergraduate student, graduate student, or recent graduate pursuing or earned a degree in a discipline related to High Performance Computing

## BENEFITS

- Stipend starting at \$700/week\*
- Housing allowance of \$150/week\*\*
- Training/Research allowance up to \$250
- Travel reimbursement up to \$2,000\*\*

\* Based on academic level at time of internship | \*\* If eligible

**DURATION** May – September 2023 (10 consecutive weeks)

**LOCATION** DOE National Laboratories



The High Performance Computing for Manufacturing Internship Program is sponsored by the Advanced Materials and Manufacturing Technologies Office (AMMTO) within the Office of Energy Efficiency & Renewable Energy (EERE).